Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **CLEAR**
2. **CLOCK**
3. **A**
4. **B**
5. **C**
6. **D**
7. **ENABLE P**
8. **GND**
9. **LOAD**
10. **ENABLE T**
11. **QD**
12. **QC**
13. **QB**
14. **QA**
15. **RIPPLE CARRY**
16. **VCC**

**.064”**

**.071”**

 **1 16**

**15**

**14**

**13**

**12**

**11**

**2**

**3**

**4**

**5**

**6**

 **7 8 9 10**

**MASK**

**REF**

**4161B**

**1**

**Top Material: Al**

 **Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential:**

**Mask Ref: 4161B**

**APPROVED BY: DK DIE SIZE .064” X .071” DATE: 1/25/22**

**MFG: SOLID STATE SEMI THICKNESS .020” P/N: CD40161B**

**DG 10.1.2**

#### Rev B, 7/1